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# NSDEMP11XV6T1, NSDEMP11XV6T5

## Common Anode Quad Array Switching Diode

These Common Anode Epitaxial Planar QUAD Diodes are designed for use in ultra high speed switching applications. The NSDEMP11XV6T1 device is housed in the SOT-563 package which is designed for low power surface mount applications, where board space is at a premium.

### Features

- Fast  $t_{rr}$
- Low  $C_D$
- These are Pb-Free Devices

### MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ )

Rating	Symbol	Value	Unit
Reverse Voltage	$V_R$	80	Vdc
Peak Reverse Voltage	$V_{RM}$	80	Vdc
Forward Current	$I_F$	100	mAdc
Peak Forward Current	$I_{FM}$	300	mAdc
Peak Forward Surge Current	$I_{FSM}$ (Note 1)	2.0	Adc

### THERMAL CHARACTERISTICS

Characteristic (One Junction Heated)	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^\circ\text{C}$	$P_D$	357 (Note 2)	mW
Derate above $25^\circ\text{C}$		2.9 (Note 2)	mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	350 (Note 2)	$^\circ\text{C}/\text{W}$
Characteristic (Both Junctions Heated)	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^\circ\text{C}$	$P_D$	500 (Note 2)	mW
Derate above $25^\circ\text{C}$		4.0 (Note 2)	mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	250 (Note 2)	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

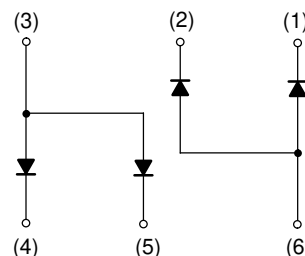
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1.  $t = 1 \mu\text{s}$
2. FR-4 @ Minimum Pad



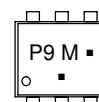
ON Semiconductor®

<http://onsemi.com>



SOT-563  
CASE 463A  
PLASTIC

### MARKING DIAGRAM



P9 = Device Code  
M = Date Code  
▪ = Pb-Free Package  
(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping†
NSDEMP11XV6T1	SOT-563*	4000/Tape & Reel
NSDEMP11XV6T1G	SOT-563*	4000/Tape & Reel
NSDEMP11XV6T5	SOT-563*	8000/Tape & Reel
NSDEMP11XV6T5G	SOT-563*	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*This package is inherently Pb-Free.

# NSDEMP11XV6T1, NSDEMP11XV6T5

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ )

Characteristic	Symbol	Condition	Min	Max	Unit
Reverse Voltage Leakage Current	$I_R$	$V_R = 70\text{ V}$	-	0.1	$\mu\text{A}$ dc
Forward Voltage	$V_F$	$I_F = 100\text{ mA}$	-	1.2	Vdc
Reverse Breakdown Voltage	$V_R$	$I_R = 100\text{ }\mu\text{A}$	0	-	Vdc
Diode Capacitance	$C_D$	$V_R = 6.0\text{ V}, f = 1.0\text{ MHz}$	-	3.5	pF
Reverse Recovery Time	$t_{rr}$ (Note 3)	$I_F = 5.0\text{ mA}, V_R = 6.0\text{ V}, R_L = 100\text{ }\Omega, I_{rr} = 0.1 I_R$	-	4.0	ns

3.  $t_{rr}$  Test Circuit for NSDEMP11XV6T1 in Figure 4.

## TYPICAL ELECTRICAL CHARACTERISTICS

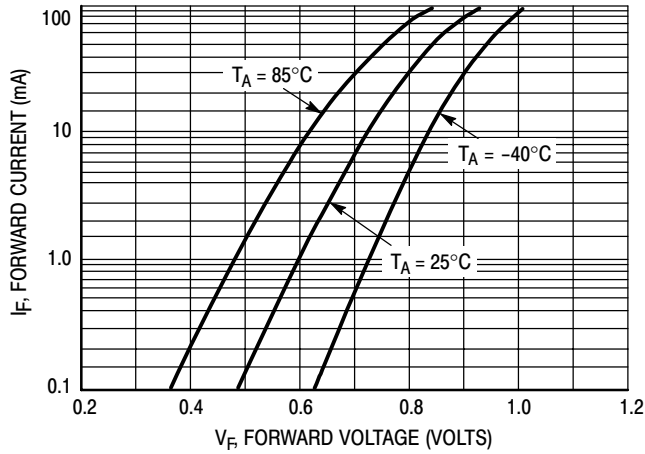


Figure 1. Forward Voltage

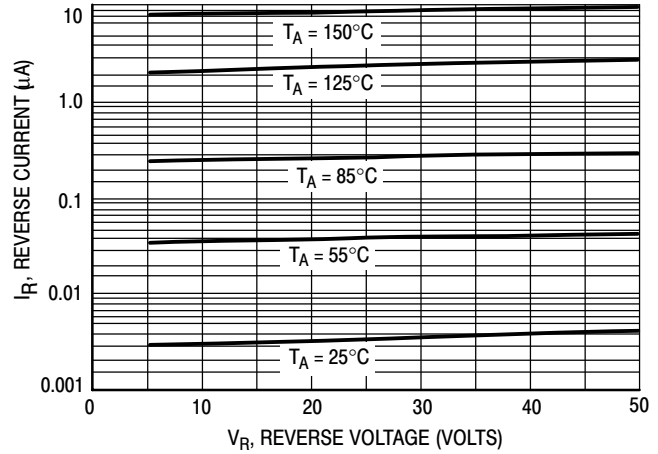


Figure 2. Reverse Current

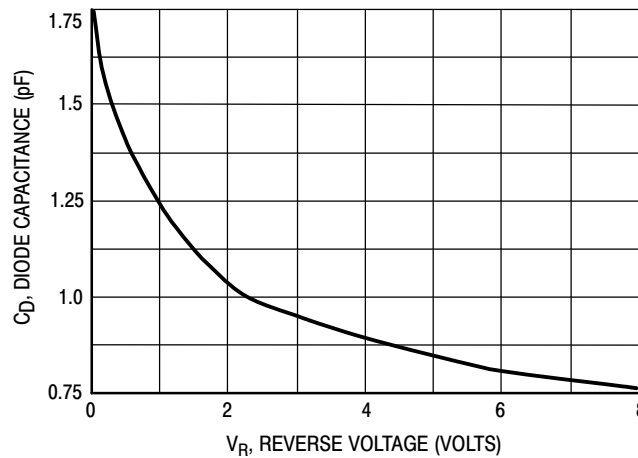


Figure 3. Diode Capacitance

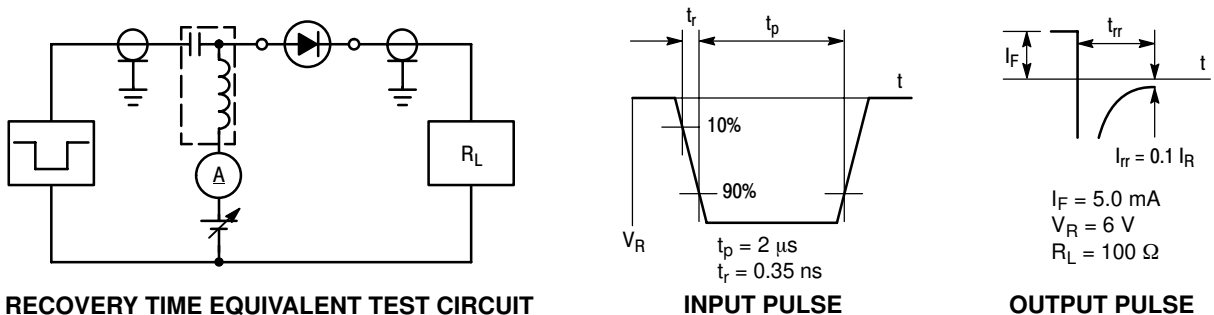
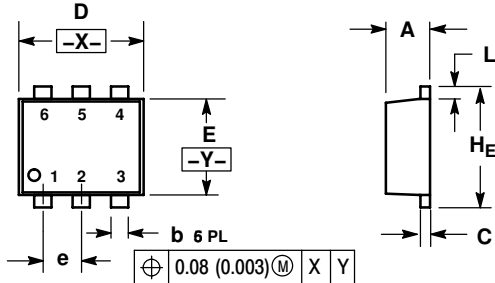


Figure 4. Reverse Recovery Time Test Circuit for the NSDEMP11XV6T1

# NSDEMP11XV6T1, NSDEMP11XV6T5

## PACKAGE DIMENSIONS

SOT-563, 6 LEAD  
CASE 463A-01  
ISSUE F

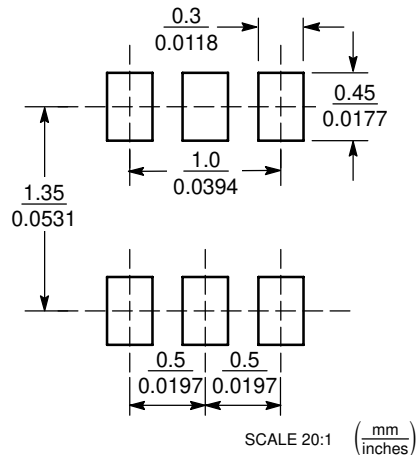


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.55	0.60	0.020	0.021	0.023
b	0.17	0.22	0.27	0.007	0.009	0.011
C	0.08	0.12	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.062	0.066
E	1.10	1.20	1.30	0.043	0.047	0.051
e	0.5 BSC			0.02 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
H <sub>E</sub>	1.50	1.60	1.70	0.059	0.062	0.066

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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